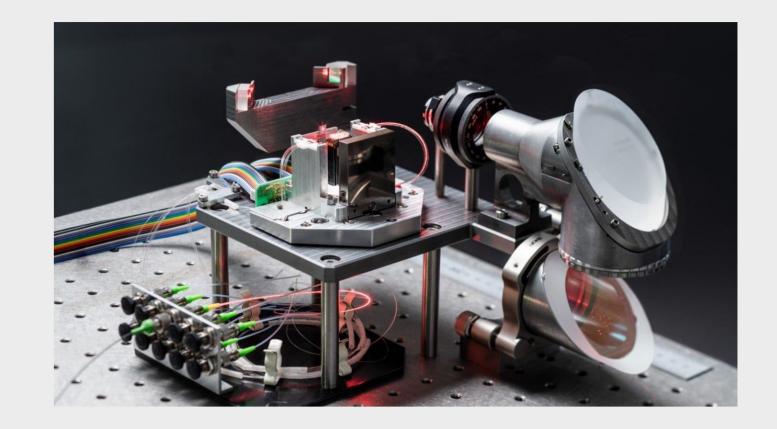


Optical actuation and control systems

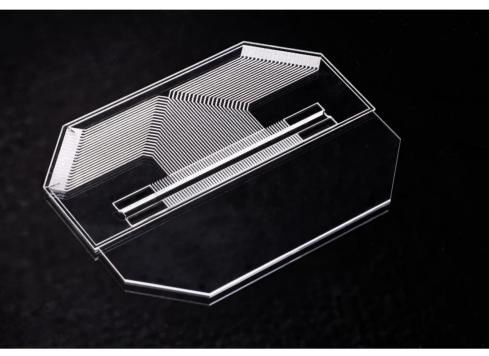
Addressing units for ion- and atom-based quantum computers





Application:

- Individual addressing of ions in an ion trap or atoms in an optical lattice
- Spacing of the addressing zones
- Ions: 5 µm (irregular, linear)
- Atoms: 1 µm (regular, 2D)



SiO₂ Etched ion trap

2 Technology

Optical and mechanical design

- Zeemax and Lumerical simulations
- Multi-physics finite-element analysis

Microlens production

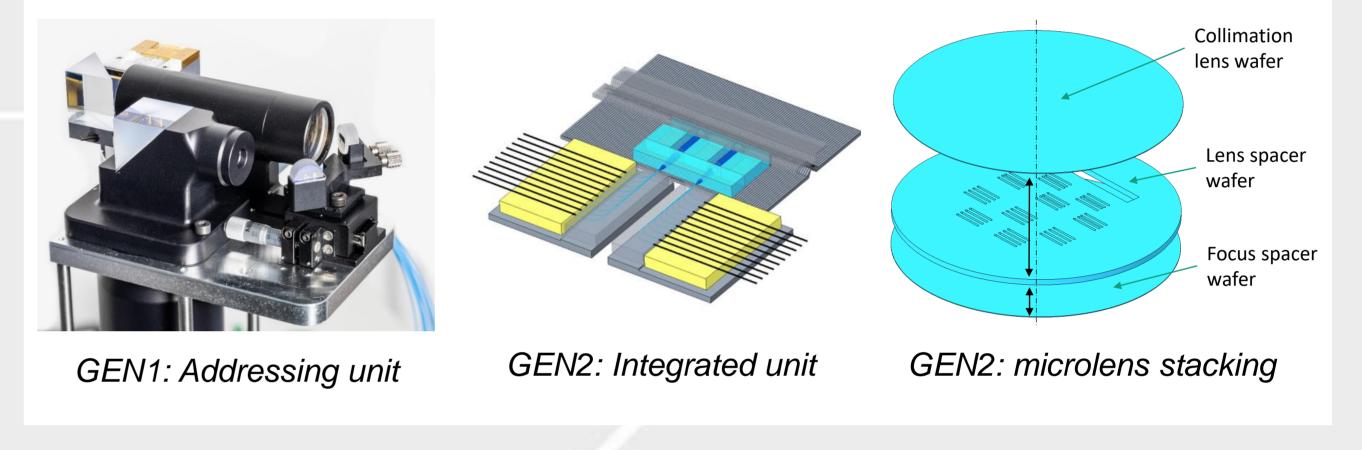
- Reflow microlens array (MLA) production
- Creation of reproduction master by means of lithography
- Polymer apertures and anti-reflective coatings



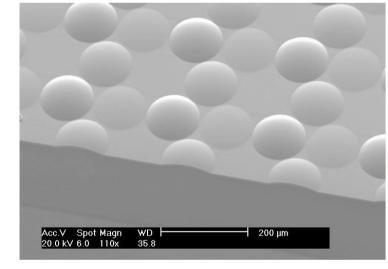
Combined mechanical and optical design

GEN1: external addressing unit

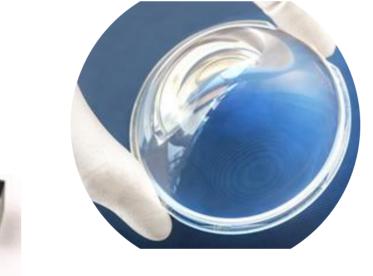
- Parallel manipulation of 10 ions lined up next to each other
- Fiber-coupled waveguide as input, collimated with microlens array **GEN2: integrated addressing unit**
- Waveguide and microlenses assembled onto ion trap chip
- Microlenses pre-assembled using wafer stacking process **Specifications**:
- Spot size: 2 μm, spot distance: ~ 5 μm, wavelength: 400 nm



4 Atom addressing unit (FermiQP)



MLA chip of the addressing unit

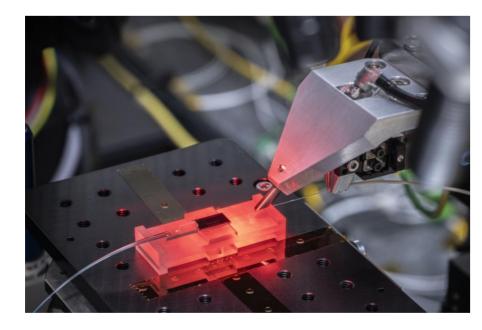


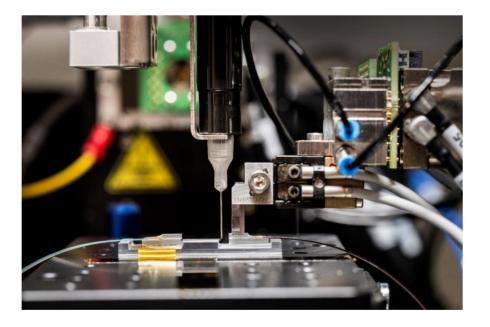
MLA with different focal lengths

Anti-reflective coating

Integration

- Active alignment of optical components (fibers, lenses, mirrors)
- Ultra-low-loss polarization aligned fiber to chip coupling





Single fiber alignment

Fiber array bonding

Ultra-high-vacuum connection technology

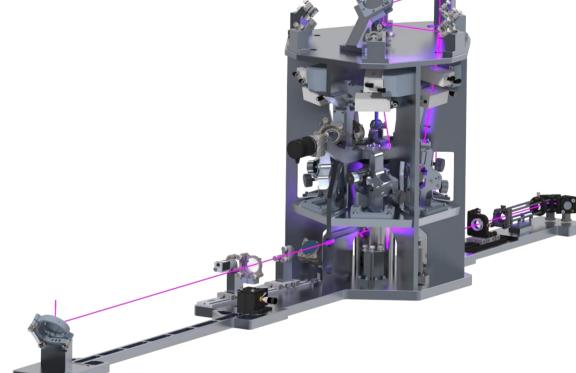
- UHV compatible UV-curing adhesives
- Solder jet laser soldering for precession joints of optics
- Inorganic silicate bonding for optical interfaces
- Direct bonding for covalent connections of joining partners

Specifications:

- Addressing for 400 lithium atoms
- Telecentric imaging with analog micromirror array
- Diffractive beam splitter for splitting into 6 sub-beams
- Wavelength: 323 nm, spot size: 0.4 1 μm (customizable)



Mirror array with individually tilted 50 x 50 μm² micromirrors

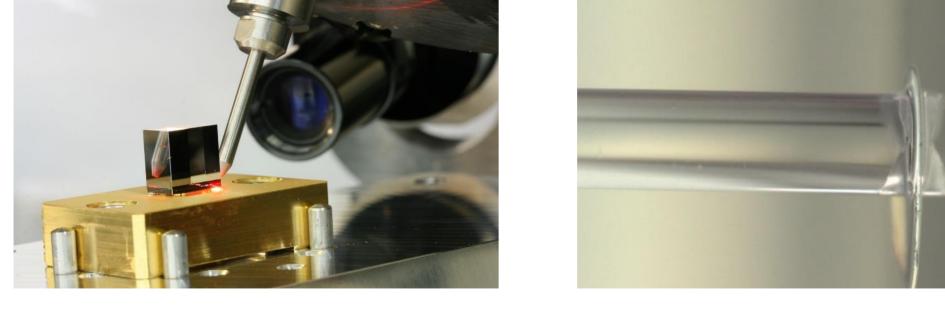


Design of the FermiQP structure

5 Development of integrated systems

Objective:

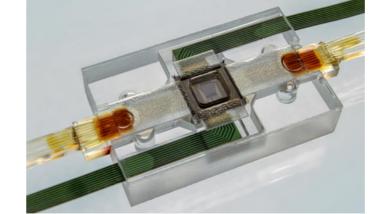
• Integrated scalable addressing units using integrated photonics



Solderjet bumping

Silicate bonding

(PICs and micro-optics)



SiN-QPIC for neutral atom manipulation

Integrated in SLE-structured, hermetic glass package, optical fibers and electronics

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